



## Customer Information Notification

202207007I : i.MX 8M Nano Reference Manual Update to Rev 2

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Nov 25, 2022 **Effective date:** Nov 26, 2022

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For detailed information we invite you to [view this notification online](#)

### Management summary

Reference manual update for i.MX 8M Nano to revision 2.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage

☐ Firmware ☒ Other: Reference Manual

## PCN Overview

### Description

NXP Semiconductors announces reference manual update for i.MX 8M Nano to revision 2. The revision history included in the updated document provides a detailed description of the changes.  
Reference manual Changes Summary:

1. Chapter 1, Introduction
2. Chapter 2, Memory Map
3. Chapter 6, SNVS, Reset, Fuse, and Boot
4. Chapter 11, Connectivity
5. Chapter 13, Multimedia
6. Thermal Monitoring Unit (TMU)

Above chapters have been updated, details refer to RM revision history.

This evaluation has been successfully completed according to NXP specifications.  
Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02

The i.MX 8M Nano reference manual Rev.2 are attached to this notice, and can be found at:  
<https://www.nxp.com/webapp/Download?colCode=IMX8MNRM>

## Reason

The Reference Manuals have been updated for chapter contents and provide additional technical clarification on some device features.

## Identification of Affected Products

Product identification does not change

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

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No Impact on form, fit, function, reliability or quality

## Additional information

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Additional documents: [view online](#)

## Contact and Support

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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